Introduction

The purpose of this application note is to show how to improve the accuracy of A/D conversions for applications using the STM32F2xx and STM32F4xx microcontrollers.

It also explains the firmware methodology, which can be applied to reduce the ADC error and gives some general tips on writing firmware for better ADC accuracy.

Please note that the data provided with this application note is for reference only, measured in a lab under typical conditions (unless specified otherwise) and not tested in production. Table 1 lists the microcontrollers concerned by this application note.

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<table>
<thead>
<tr>
<th>Type</th>
<th>Part numbers</th>
</tr>
</thead>
<tbody>
<tr>
<td>Microcontrollers</td>
<td>STM32F2xx (STM32F20x, STM32F21x)</td>
</tr>
<tr>
<td></td>
<td>STM32F4xx (STM32F405, STM32F407, STM32F415, STM32F417, STM32F42x, STM32F43x)</td>
</tr>
</tbody>
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1 Overview of parameters impacting the ADC accuracy

The accuracy of an analog to digital conversion has an impact on the overall system quality and efficiency. To improve the accuracy, you need to understand the errors associated with the ADC and the parameters affecting them.

The ADC, itself, cannot ensure the accuracy of results. It depends on your overall system design. For this reason, you need to do some careful preparation before starting your development.

Many parameters impact the ADC accuracy, depending on the application. Some of these factors are: PCB layout, voltage source, I/O switching and analog source impedance.

For more details about ADC errors, please refer to AN2834: *How to get the best ADC accuracy in STM32F10xxx devices* and to AN3137: *A/D converter on STM8L devices* application notes.
2 Firmware techniques for improving the conversion accuracy

2.1 Averaging

Averaging is a simple technique where you sample an analog input several times and take the average of the results. This technique is helpful to eliminate the effect of noise on the analog input or a wrong conversion.

2.1.1 Averaging of N ADC samples

When this method is used, it is better to collect the samples in multiples of 2 (N should be a multiple of 2). This makes it more efficient to compute the average because you can do the division by right-shifting the sum of the converted values. This saves CPU time and code memory needed to execute a division algorithm (in Cortex-Mx, this takes 1 CPU cycle).

![Figure 1. Graphical representation of averaging technique](image)

This averaging technique is used to measure the voltage on one analog input pin. A total of N conversions is considered and the average is calculated. This is done in a loop in the firmware.
Total conversion time = (number of samples * ADC conversion time) + computation time.

Computation time = time taken to read the results, add them together and calculate the average by dividing the total by the number of samples.

There is a trade-off between the total conversion time and the number of samples used to average, depending on the analog signal variations and the time available for computation.

Note: Refer to Appendix A for more details about the code source used.

### 2.1.2 Averaging of N-X ADC samples

This method is based on taking N ADC samples, sorting them from the highest to the lowest value (or the reverse) and deleting the dispersed X samples.

It is recommended to choose N and X as multiples of 2.

This averaging method is more efficient than the previous one, as it deletes the most dispersed values which could impact the average, and it gives a good trade-off between the execution time and the conversion accuracy.
Total conversion time = (number of samples * ADC conversion time) + computation time.

Computation time = time taken to read the results, sort the N ADC samples, delete the X most dispersed samples, add the rest of the ADC samples together and calculate the average by dividing the total by N-X.

Note: Refer to Appendix B for more details about the code source used.
2.2 Additional recommendation

ADC conversion results are the ratio of the input voltage to the reference voltage. If there is noise in the reference voltage, then the results may not be accurate. Both hardware and firmware design are responsible for reducing the noise.

The execution of code generates some non-negligible noise on the internal power supply network of the microcontroller. To filter this noise, the $V_{DDA}$ (or $V_{REF}$) and $V_{SSA}$ analog supply pins are available on the microcontroller package; you can connect a capacitor analog filter to these power supply pins to filter a high frequency noise.

Here are some general firmware design tips for reducing system noise in order to achieve a better ADC conversion accuracy:

1. Avoid starting transmission on any communication peripheral just before starting the ADC conversion. The toggling of the I/Os may create some noise in the supply voltage.
2. Avoid toggling high-sink I/Os which cause noise ripples in the power supply.
3. Avoid toggling digital outputs on the same I/O port as the A/D input is being converted. This can introduce switching noise into the analog inputs.
4. It is recommended to configure the STM32F2/F4 ART with data cache + Instruction cache enable and to disable the prefetch. This will avoid extra CPU accesses to the Flash memory causing an additional noise which can significantly decrease the ADC accuracy in some applications.
3 STM32F2 and STM32F4 practical measurements

This section only applies to all STM32F2xx, STM32F405, STM32F415, STM32F407 and STM32F417 microcontrollers.

This section gives some ADC accuracy measurements, putting the previously described methods into practice.

3.1 Measurement conditions

3.1.1 Hardware setup

- STM32F407ZGT6 soldered on a test board (with only a minimum number of other hardware components)
- Ambient temperature: 25°C
- 3 power supplies are applied to the MCU: V_{DD}/V_{SS}, V_{DDA}/V_{SSA}, V_{REF+}/V_{REF-}.
- Power supply range: V_{DD}=V_{DDA}=V_{REF+} = 3.3 V, f_{ADC} = 36 MHz
- Clock source: external clock (8 MHz) provided by a generator, PLL is enabled, f_{CPU} = 144 MHz
- Three fixed analog input voltages are tested: 0.3 V, 1.65 V and 3 V

3.1.2 Firmware setup

- ADC channel 2 is used in single conversion mode
- 50000 acquisitions were taken for each fixed analog input voltage
- Five firmware methods were used to examine the ADC converted data:
  - Raw data (without averaging)
  - Averaging of 4 ADC samples
  - Averaging of 6 ADC samples
  - Averaging of 8 ADC samples
  - Averaging of 8 ADC samples and deleting the 4 most dispersed samples

Note: All tests were done with f_{ADC} = 36 MHz, sampling time = 3 ADC cycles and ADC resolution = 12 bits in order to achieve the fastest ADC conversion (2.4 Msps).

3.2 Results

These measurements have been done based on a characterization of the ADC and are confirmed by further investigations (about 100 tests), where many parameters were evaluated to analyze the impact of each one.

The following measurements were considered while evaluating the impact of three different ART configurations on the ADC accuracy:

- ART ON: (data cache + instruction cache + prefetch) ON
- ART OFF: (data cache + instruction cache + prefetch) OFF
- (Data cache + instruction cache) ON + prefetch OFF
Note: All results are evaluated versus a dispersion range of +/-5 LSB around the value which occurred the most in the histogram (see Figure 4).

Figure 4. Histogram graphical representation versus code dispersion

3.2.1 ADC measurements when ART is ON

*Table 2* and *Figure 5* show the ADC code distribution when ART is ON.

<table>
<thead>
<tr>
<th>$V_{IN}$</th>
<th>Raw data</th>
<th>Averaging by 4</th>
<th>Averaging by 6</th>
<th>Averaging by 8</th>
<th>Averaging by 8 delete 4</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Dispersion (LSB)</td>
<td>Sample over +/-5 LSB</td>
<td>Dispersion (LSB)</td>
<td>Sample over +/-5 LSB</td>
<td>Dispersion (LSB)</td>
</tr>
<tr>
<td>0.3 V</td>
<td>19</td>
<td>6.37 %</td>
<td>10</td>
<td>0 %</td>
<td>9</td>
</tr>
<tr>
<td>1.65 V</td>
<td>21</td>
<td>7.90 %</td>
<td>13</td>
<td>0.05 %</td>
<td>10</td>
</tr>
<tr>
<td>3 V</td>
<td>21</td>
<td>21.53 % (1)</td>
<td>15</td>
<td>0.38 %</td>
<td>13</td>
</tr>
</tbody>
</table>

1. Worst case found in a total of more than 100 tests
3.2.2 ADC measurements when ART is OFF

Table 3 and Figure 6 show the ADC code distribution when ART is OFF.

<table>
<thead>
<tr>
<th>$V_{IN}$</th>
<th>Raw data</th>
<th>Averaging by 4</th>
<th>Averaging by 6</th>
<th>Averaging by 8</th>
<th>Averaging by 8 delete 4</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Dispersion (LSB)</td>
<td>Sample over +5 LSB</td>
<td>Dispersion (LSB)</td>
<td>Sample over +5 LSB</td>
<td>Dispersion (LSB)</td>
</tr>
<tr>
<td>0.3 V</td>
<td>18</td>
<td>4.07 %</td>
<td>11</td>
<td>0.004</td>
<td>9</td>
</tr>
<tr>
<td>1.65 V</td>
<td>20</td>
<td>5.99 %</td>
<td>11</td>
<td>0.01 %</td>
<td>11</td>
</tr>
<tr>
<td>3 V</td>
<td>24</td>
<td>16.28 %</td>
<td>18</td>
<td>6.92 %</td>
<td>13</td>
</tr>
</tbody>
</table>

1. Worst case found in a total of more than 100 tests
Figure 6. Distribution of ADC codes when ART is OFF and $V_{IN} = 1.65\,\text{V}$
3.2.3 ADC measurements when (Data+Instruction) cache ON+prefetch OFF

Table 4 and Figure 7 to Figure 9 show the ADC code distribution when the (Data+Instruction) cache is ON and prefetch is OFF.

Table 4. Distribution of ADC codes when (Data+Instruction) cache ON + prefetch OFF (units in LSB)

<table>
<thead>
<tr>
<th>$V_{IN}$</th>
<th>Raw data</th>
<th>Averaging by 4</th>
<th>Averaging by 6</th>
<th>Averaging by 8</th>
<th>Averaging by 8 delete 4</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Dispersion (LSB)</td>
<td>Sample over +-5 LSB</td>
<td>Dispersion (LSB)</td>
<td>Sample over +-5 LSB</td>
<td>Dispersion (LSB)</td>
</tr>
<tr>
<td>0.3 V</td>
<td>16</td>
<td>0.06 %</td>
<td>7</td>
<td>0 %</td>
<td>5</td>
</tr>
<tr>
<td>1.65 V</td>
<td>18</td>
<td>0.064 %</td>
<td>8</td>
<td>0 %</td>
<td>6</td>
</tr>
<tr>
<td>3 V</td>
<td>17</td>
<td>0.068 %</td>
<td>8</td>
<td>0 %</td>
<td>6</td>
</tr>
</tbody>
</table>

Figure 7. Distribution of ADC codes when (D+I) cache ON + prefetch OFF $V_{IN} = 0.3$ V
3.3 Timing considerations

The following table gives an idea of the execution time of each averaging algorithm in terms of CPU cycles.
Note: These timing measurements are considered based on the optimum ART configuration: (Data+Instruction) cache ON, Prefetch OFF, which results in the best ADC noise immunity. In other ART configurations, these measurements could result in a difference of a few cycles.

<table>
<thead>
<tr>
<th>Computation time</th>
<th>Averaging by 4 (1)</th>
<th>Averaging by 6 (1)</th>
<th>Averaging by 8 (1)</th>
<th>Averaging by 8, delete 4 (2)</th>
</tr>
</thead>
<tbody>
<tr>
<td>CPU cycles (3)</td>
<td>18</td>
<td>26</td>
<td>36</td>
<td>517</td>
</tr>
</tbody>
</table>

Note: Please note that the time required to get N samples = \( N \times (t_{\text{SAMPLING}} + t_{\text{CONVERSION}}) \)

3.4 Measurement conclusion

Following the previous results, we can conclude that, in order to obtain the most accurate conversion results when using the STM32F2/F405/F415/F407/F417 ADC, care must be taken to configure the ART Flash memory accelerator accordingly. This configuration must be (Data+Instruction) ON and prefetch OFF to achieve the best accuracy by limiting the internal noise generated by the Flash.

This section shows how you can choose the best trade-off between A/D conversion accuracy and the required A/D conversion speed.

For example, the measurements given above demonstrate that, with a 12-bit ADC resolution, ± 5 LSB can be achieved using an averaging by 4 algorithm (0.6 Msps) when the ART Flash memory accelerator is configured with (Data+Instruction) ON and prefetch OFF.
4 STM32F4 ADC accuracy options

This section only applies to STM32F42x/F43x microcontrollers.

Before describing the STM32F42x and STM32F43x ADC evaluation results, the silicon configurable options embedded on these products to enhance the ADC accuracy will be detailed.

4.1 Configuration options for ADC accuracy

By default, on these products, noise filtering techniques are activated internally between the ADC analog block and other microcontroller blocks. These techniques will reduce the power supply noise, the signal crosstalk and the EMI-induced noise. For more details about practical ADC results in this condition, please refer to section 4.2.3.

To further improve the ADC accuracy, two configurable options are available. The following names are used throughout the document:

- Default: The default STM32 configuration which is always active out of reset.
- Option 1: The first configurable option which can be activated by firmware.
- Option 2: The second configurable option which can be activated by firmware.

4.1.1 Option 1

This option can be activated or not by firmware. By default, it is not active. When activated by firmware, it continuously masks the extra flash access generated by the prefetch mechanism which can produce random noise impacting the ADC accuracy.

This could be activated by setting the ADCDC1 (bit 13) in the PWR_CR register.

Warning: This bit can only be set at the following conditions:
- Prefetch must be OFF.
- VDD voltage ranges from 2.4 V to 3.6 V.
- This bit must not be set when the ADCxDC2 bit in SYSCFG_PMC register is set.

For more details about the exact firmware sequence to enable Option 1, please refer to Section C.1: Option 1.

The ADC accuracy results when activating this option, will be detailed in next section.

4.1.2 Option 2

This option can be activated or not by firmware. By default, it is not active. When activated by firmware, it masks the internal flash noise during the last ADC sampling cycle. This will improve the ADC immunity versus internal spurious flash noise.
This could be activated by setting the ADCxDC2 (bit 16 - bit18) in the SYSCFG_PMC register.

---

**Warning:** These bits can only be set at the following conditions:
- Minimum ADC clock is 30MHz.
- Only one ADCxDC2 bit must be selected in case ADC conversion does not start at the same time and different sampling times are used.
- ADC resolution should be equal to 12 bits.
- This bit must not be set when the ADCDC1 bit in PWR_CR register is set.

---

In this option, one bit for each ADC is available in SYSCFG_PMC register. There is more flexibility to enable or not this option for each ADC separately.

As stated in the warning above, these three bits should not be activated simultaneously in some conditions.

Following are the ADC modes versus the simultaneously usage of ADCxDC2 bits:

**Table 6. ADCxDC2 usage versus ADC mode**

<table>
<thead>
<tr>
<th>Single mode (1)</th>
<th>Multi ADC Modes</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Injected simultaneous</td>
</tr>
<tr>
<td>One ADCxDC2</td>
<td>YES</td>
</tr>
<tr>
<td>Some or all ADCxDC2</td>
<td>NO</td>
</tr>
</tbody>
</table>

1. When two or three ADCs are activated separately and each one is configured in single mode, only one ADCxDC2 bit should be used.
2. Some or all ADCxDC2 bits could be used in case the same sampling time is used for all ADCs.
3. Some or all ADCxDC2 bits could be used in case the start of conversion triggers are controlled to set up an interval between each ADC end of sampling equal to or greater than 15 ADC cycles.

For more details about the exact firmware sequence to enable Option 2, please refer to Section C.2: Option 2.

The ADC accuracy when activating this option will be detailed in the next section.

### 4.2 Practical measurements

In this section, practical ADC measurements are done in order to demonstrate the impact of these ADC accuracy options.
4.2.1 Hardware Setup

The hardware environment used for the ADC tests is the same as the one described in Section 3.1.1: Hardware setup, with the use of STM32F43x.

4.2.2 Common firmware setup

- ADC1 Channel 1 is used in single conversion mode,
- The sampling time is fixed to 3 ADC clock cycles,
- 50000 acquisition was taken for each fixed analog input voltage,

All tests are done with FADC = 36 MHz, sampling time= 3 ADC cycles and ADC resolution = 12 bits in order to achieve the fastest ADC conversion which is equal to 2.4 MSPS.

4.2.3 Results

The following measurements were taken while evaluating the impact of the ADC accuracy options embedded on these products at three different ART configurations which are:

- ART ON: (data cache + instruction cache + prefetch) ON,
- ART OFF: (data cache + instruction cache + prefetch) OFF,
- (Data cache + instruction cache) ON + Prefetch OFF

1. ADC measurements when ART is ON

The following table and graph show the ADC code distribution when ART is ON at two different conditions: Default STM32 configuration and when Option 2 is active:

<table>
<thead>
<tr>
<th>$V_{IN}$</th>
<th>Default</th>
<th>Option 1</th>
<th>Option 2</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Dispersion (LSB)</td>
<td>sample over +5 LSB</td>
<td>Dispersion (LSB)</td>
</tr>
<tr>
<td>$0.3 \text{ V}$</td>
<td>7</td>
<td>0%</td>
<td>(1)</td>
</tr>
<tr>
<td>$1.65 \text{ V}$</td>
<td>9</td>
<td>0%</td>
<td></td>
</tr>
<tr>
<td>$3 \text{ V}$</td>
<td>7</td>
<td>0%</td>
<td></td>
</tr>
</tbody>
</table>

1. Option 1 is not applicable since Prefetch is ON in this case.
In the same conditions, when ART is ON, using the default STM32 configuration with STM32F2xx or STM32F405/F415/F407/F417 would give a maximum dispersion of 21 LSB (refer to Table 2) while, in this case, the maximum dispersion is 9 LSB.

This confirms that the default STM32 configuration embedded on these products allows to achieve about 50 % of dispersion code versus STM32F2xx/F405/F415/F407/F417, and about 75 % when Option 2 is active.

2. ADC measurements when ART is OFF

The following table and graph show the ADC code distribution when ART is OFF at three different conditions: Default STM32 configuration, Option 1 and Option 2 are active.

Table 8. Distribution of ADC codes when ART is OFF

<table>
<thead>
<tr>
<th>V_IN</th>
<th>Default</th>
<th>Option 1</th>
<th>Option 2</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Dispersion (LSB)</td>
<td>sample over +5 LSB</td>
<td>Dispersion (LSB)</td>
</tr>
<tr>
<td>0.3 V</td>
<td>9</td>
<td>0%</td>
<td>5</td>
</tr>
<tr>
<td>1.65 V</td>
<td>10</td>
<td>0%</td>
<td>7</td>
</tr>
<tr>
<td>3 V</td>
<td>8</td>
<td>0%</td>
<td>6</td>
</tr>
</tbody>
</table>
In the same conditions, when ART is OFF, using the Default STM32 configuration with STM32F2xx or STM32F405/F415/F407/F417 gives a maximum dispersion of 24 LSB (refer to Table 3) while, in this case, the maximum dispersion is 10 LSB.

This confirms that the default STM32 configuration embedded on these products allows to achieve more than 50 % of dispersion code versus STM32F2xx/F405/F415/F407/F417, and about 75 % when one of the options is active.

3. ADC measurements when (Data+Instruction) cache ON + Prefetch OFF

The following table and graph show the ADC code distribution when (Data + Instruction) cache ON and prefetch OFF at three different conditions: default STM32 configuration, Option 1 and Option 2 are active.

Table 9. Distribution of ADC codes when (Data+Instruction) cache ON + prefetch OFF

<table>
<thead>
<tr>
<th>VIN</th>
<th>Default</th>
<th>Option 1</th>
<th>Option 2</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Dispersion (LSB)</td>
<td>sample over +-5 LSB</td>
<td>Dispersion (LSB)</td>
</tr>
<tr>
<td>0.3 V</td>
<td>7</td>
<td>0%</td>
<td>4</td>
</tr>
<tr>
<td>1.65 V</td>
<td>8</td>
<td>0%</td>
<td>6</td>
</tr>
<tr>
<td>3 V</td>
<td>7</td>
<td>0%</td>
<td>6</td>
</tr>
</tbody>
</table>
In the same conditions, when (Data+Instruction) cache ON and Prefetch OFF, using the Default STM32 configuration with STM32F2xx or STM32F405/F415/F407/F417 gives a maximum dispersion of 18 LSB (refer to Table 4) while, in this case, the maximum dispersion is 8 LSB.

This confirms that the default STM32 configuration embedded on these products allows to achieve about 50% of dispersion code versus STM32F2xx/F405/F415/F407/F417, and about 75% when one of the options is active.

Figure 12. Distribution of ADC codes when (D+I) cache ON + Prefetch OFF \( V_{IN} = 0.3 \) V
Figure 13. Distribution of ADC codes when (D+I) cache ON + Prefetch OFF \( \text{V}_{\text{IN}} = 1.65 \text{V} \)

Figure 14. Distribution of ADC codes when (D+I) cache ON + Prefetch OFF \( \text{V}_{\text{IN}} = 3 \text{ V} \)
4.3 Measurement conclusions

Based on these measurements and comparing to STM32F2xx and STM32F405/F415/F407/ F417 measurements, we can conclude that ADC accuracy options embedded on these products allow an improvement of the ADC code dispersion up to 75%.

For the applicable products, you can choose either to work with the default configuration or to enable one of the options; It depends on the ADC precision required by the application.

Based on these typical measurements, to achieve the best ADC accuracy with these products, you need to know that:

- For the Default configuration: Prefetch OFF + Data cache ON + Instruction cache ON gives a maximum of 8 codes of dispersion.
- When activating Option 1: Prefetch OFF + Data cache ON + Instruction cache ON gives a maximum of 6 codes of dispersion.
- When activating Option 2: Prefetch ON + Data cache ON + Instruction cache ON gives a maximum of 6 codes of dispersion.

However, Options 1 and 2 should only be applied in specific conditions as detailed above (refer to Section 4.1) to avoid any MCU malfunction.
/**
 * @brief   Get the average of N ADC samples
 * @param Numbre of ADC samples to be averaged
 * @retval The average value
 */

uint16_t ADC_GetSampleAvgN(uint8_t N)
{
    uint32_t avg_sample =0x00;
    uint16_t adc_sample[8]={0,0,0,0,0,0,0,0};
    uint8_t index=0x00;

    /* Get the N ADC samples */
    for (index=0x00; index<N; index++)
    {
        /* ADC start conv */
        ADC_SoftwareStartConv(ADC1);
        /* Wait end of conversion */
        while(ADC_GetFlagStatus(ADC1,ADC_FLAG_EOC) == RESET);
        /* Store ADC samples*/
        adc_sample[index] = ADC_GetConversionValue(ADC1);
    }

    /* Add the N ADC samples */
    for (index=0; index<N; index++)
    {
        avg_sample += adc_sample[index];
    }

    /* Compute the average of N ADC samples */
    avg_sample /= N;

    /* Return average value*/
    return avg_sample;
}
/**
 * @brief Get the average of N-X ADC samples
 * @param Numbre of ADC samples to be averaged
 * @param Numbre of ADC samples to be averaged
 * @retval The average value
 */
uint16_t ADC_GetSampleAvgNDeleteX(uint8_t N, uint8_t X)
{
    uint32_t avg_sample = 0x00;
    uint16_t adc_sample[8] = {0, 0, 0, 0, 0, 0, 0, 0};
    uint8_t index = 0x00;

    for (index = 0x00; index < N; index++)
    {
        /* ADC start conv */
        ADC_SoftwareStartConv(ADC1);
        /* Wait end of conversion */
        while (ADC_GetFlagStatus(ADC1, ADC_FLAG_EOC) == RESET);
        /* Store ADC samples */
        adc_sample[index] = ADC_GetConversionValue(ADC1);
    }

    /* Sort the N-X ADC samples */
    Sort_tab(adc_sample, N);

    /* Add the N ADC samples */
    for (index = X / 2; index < N - X / 2; index++)
    {
        avg_sample += adc_sample[index];
    }

    /* Compute the average of N-X ADC sample */
    avg_sample /= N - X;

    /* Return average value */
    return avg_sample;
}
void Sort_tab(uint16_t tab[], uint8_t lenght)
{
    uint8_t l=0x00, exchange =0x01;
    uint16_t tmp=0x00;

    /* Sort tab */
    while(exchange==1)
    {
        exchange=0;
        for(l=0; l<lenght-1; l++)
        {
            if( tab[l] > tab[l+1] )
            {
                tmp = tab[l];
                tab[l] = tab[l+1];
                tab[l+1] = tmp;
                exchange=1;
            }
        }
    }
}
Appendix C  Firmware sequence to activate Option 1 and Option 2

C.1  Option 1

/**<n*/
* @brief Enables or disables the ADC Option 1 configuration.<n>* @param NewState: new state of the ADCDC1 bit.<n>* This parameter can be: ENABLE or DISABLE.<n>* @retval None
* /**<n*/

void SET_ADCOption1 (FunctionalState NewState)
{
    /* ENABLE PWR clock */
    RCC_APB1PeriphClockCmd(RCC_APB1Periph_PWR, ENABLE);

    if (NewState != DISABLE)
    {
        /* Set ADCDC1 bit */
        PWR->CR |= ((uint32_t)PWR_CR_ADCDC1);
    }
    else
    {
        /* Reset ADCDC1 bit */
        PWR->CR &= (uint32_t)(~PWR_CR_ADCDC1);
    }
}
C.2 Option 2

```c
/**
 * @brief Enables or disables the ADCx Option_2 configuration.
 * @param  ADCxDC2: The ADCxDC2 bit to be used.
 *          This parameter can be one of the following values:
 *          @arg SYSCFG_PMC_ADCxDC2: All ADCxDC2 bits
 *          @arg SYSCFG_PMC_ADC1DC2: ADC1DC2 bit
 *          @arg SYSCFG_PMC_ADC2DC2: ADC2DC2 bit
 *          @arg SYSCFG_PMC_ADC3DC2: ADC3DC2 bit
 * @param  NewState: new state of the ADCxDC2 bit.
 *          This parameter can be: ENABLE or DISABLE.
 * @retval None
 */
void SET_ADCOption2 (uint32_t ADCxDC2, FunctionalState NewState) {

    /* Enable the SYSCFG clock*/
    RCC_APB2PeriphClockCmd(RCC_APB2Periph_SYSCFG, ENABLE);

    if (NewState != DISABLE) {
        /* Set the ADCxDC2 */
        SYSCFG->PMC |= (uint32_t)ADCxDC2;
    }
    else {
        /* Reset the ADCxDC2 */
        SYSCFG->PMC &= (uint32_t)(~ADCxDC2);
    }
}
```
Revision history

Table 10. Document revision history

<table>
<thead>
<tr>
<th>Date</th>
<th>Revision</th>
<th>Changes</th>
</tr>
</thead>
<tbody>
<tr>
<td>19-Mar-2012</td>
<td>1</td>
<td>Initial release.</td>
</tr>
<tr>
<td>21-Mar-2012</td>
<td>2</td>
<td>Inserted missing text on page 9.</td>
</tr>
<tr>
<td>10-Aug-2012</td>
<td>3</td>
<td>Replaced &quot;STM32F20x, STM32F21x, STM32F40x and STM32F41x microcontrollers&quot; by: &quot;STM32F20x / STM32F21x (revZ, revY, revX) and STM32F40x/STM32F41x (revZ) microcontrollers&quot; in the Introduction. Added Appendix A: Averaging of N ADC samples: source code and Appendix B: Averaging of N-X ADC samples: source code, and corresponding notes in Section 2.1.1 and Section 2.1.2.</td>
</tr>
<tr>
<td>25-Feb-2013</td>
<td>4</td>
<td>Applied to STM32F2xx (STM32F20x, STM32F21x) and STM32F4xx (STM32F40x, STM32F41x, STM32F42x, STM32F43x) microcontrollers. Section 3 now dedicated to STM32F2xx, STM32F405, STM32F415, STM32F407 and STM32F417 products, when new Section 4 is dedicated to STM32F42x/F43x products. Added Appendix C: Firmware sequence to activate Option 1 and Option 2.</td>
</tr>
<tr>
<td>02-Jul-2013</td>
<td>5</td>
<td>Changed VDD range in warning in Section 4.1.1</td>
</tr>
</tbody>
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